I hereby pertify that this sourcespondence is being deposited with the U.S. Postal Service with the Destage as First Class Mail, in an envelope addressed to:

MS Amendment, Commissioner for Patents D.O. Box 1450, Alexandria, VA 22313-1450, on the date shown below.

Dated: July 1, 2005 Signature: (Mignael R. Hull)

AF

Docket No.: 30205/38081A

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Jae H. Kim et al.

Application No.: 10/719,135

Filed: November 21, 2003

For: Chemical Mechanical Polishing Slurry for

Ruthenium Titanium Nitride and Polishing

Process Using the Same

Confirmation No.: 2226

Art Unit: 1755

Examiner: Michael A. Marcheschi

AMENDMENT IN RESPONSE TO FINAL OFFICE ACTION (37 C.F.R. §1.116)

MS AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the final Office Action dated May 4, 2005, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.